

## **MULTICHIP PACKAGE WITH CLOCK FREQUENCY ADJUSTMENT**

### **Abstract**

One embodiment of the present invention provides a multi-chip package including a logic device providing a clock signal having a frequency and a memory device. The memory device receives the clock signal and operates at the clock signal frequency. The memory device includes a temperature sensor providing a temperature signal indicative of a temperature of the memory device, wherein the logic device adjusts the clock signal frequency bases on the temperature signal.